





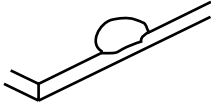




# SYSTEM MEASUREMENT SPECIFICATION

## WAFER TOPOLOGY MEASUREMENT SYSTEM

INSPECTION ITEM	MINIMUM DETECTION VALUE	ACCURACY (3σ)	ILLUSTRATION	SYSTEM IMAGE
Length, Width	50 μm	20μm		
Diagonal	50 μm	20μm		
Corner distance	140 μm	20μm		
Chamfer length	200 μm	40μm		
Rectangularity	0,1°	0,05°		
Sawmark	Step > 5 μm	2μm		



### WAFER SURFACE MEASUREMENT SYSTEM

INSPECTION ITEM	MINIMUM DETECTION VALUE	ACCURACY (3σ)	ILLUSTRATION	SYSTEM IMAGE
V-shape break	160x40 μm <sup>2</sup> or 80x80 μm <sup>2</sup>	20 μm		
Chipping	120x20 μm <sup>2</sup> or 80x80 μm <sup>2</sup>	0,001 mm <sup>2</sup>		
Pin hole	80x80 μm <sup>2</sup>	NA		
Contamination	160x120 μm <sup>2</sup>	NA		

### WAFER BOW MEASUREMENT SYSTEM

INSPECTION ITEM	MINIMUM DETECTION VALUE	ACCURACY (3σ)	ILLUSTRATION	SYSTEM IMAGE
Warp / Bow	200 μm	90 μm	